

Description

VisiC V08DI065R1X11 GaN Die is a high-density, lateral GaN power transistor with extremely low $R_{DS(ON)}$, exceptionally fast switching performance and a conveniently small footprint. It is very effective in applications requiring high current, high power density and low cost.

Key features

- Depletion Mode GaN
- No Reverse-Recovery charge
- Ultra-low On State resistance of $8m\Omega$
- Low Gate Charge
- High noise immunity with $V_{th} > 5V$
- Driven by standard 15V Si-MOSFET driver

Applications

- Automotive
- AC motors
- Solar Inverter
- AC-DC Power Supply
- Battery chargers
- Laser driver

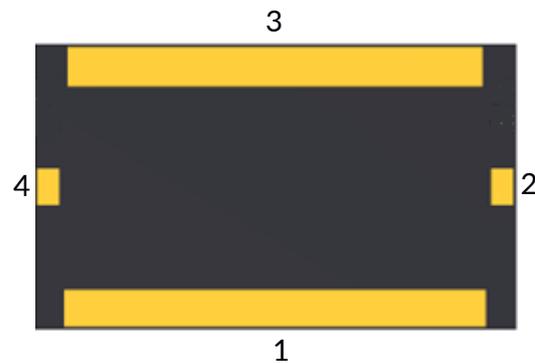


Fig. 1: Die Pinout

Key Performance Parameters

Parameter	Value	Units
V_{DS}	650	V
$R_{DS(ON)}$	8	$m\Omega$
Q_G	200	nC
$I_{D,pulse}$	450	A
I_D	200	A

Pad	Function
1	Source
2, 4	Gate
3	Drain
5 (Back Side)	Substrate

Ordering Information:

Part Number	Packing	Marking	Ordering Number
V08DI065R1X11	Tray	NA	V08DI065R1X11T

Maximum ratings (Tc =25°C unless otherwise specified)					
Parameter	Symbol	Min	Max	Unit	Conditions
Drain-Source breakdown voltage	$V_{(BR)DS}$	650	-	-	
Drain Source Transient voltage	$V_{DS(transient)}$		800	V	Pulse $\leq 1\mu s$
Continuous Drain current ¹⁾	I_D	-	280	A	$T_C = 100^\circ C^{1)}$
			170		
Pulsed Drain current ²⁾	$I_{D,pulse}$	-	450	A	
Gate Source voltage	V_{GS}	-20	0	V	
Transient Gate Source voltage	$V_{GS(transient)}$	-25	6	V	Pulse $\leq 1\mu s$
Power dissipation	P_{TOT}	-	500	W	
Operating and storage temperature	T_j, T_{stg}	-55	+150	°C	
Continuous reverse current	I_s	-	200	A	$T_C = 100^\circ C^{1)}$
Reverse pulse current ¹⁾	$I_{s,pulse}$	-	450	A	
Gate leakage	I_{gss}	-	100	nA	$V_{DS} = 650V,$ $V_{GS} = -15V$

- 1) Limited by Tj max of 150°C, Vgs = 0V, considering Rth(JC) in a discrete package = 0.1°C/W
- 2) Duty cycle =10% and pulse width limited by Tjmax.



Electrical characteristics (T _J =25°C, V _{GS} = -15V unless otherwise specified)						
Parameter	Symbol	Min	Typical	Max	Unit	Conditions
Static						
Gate threshold voltage	V _{th}	-10	-9.5	-9	V	I _D =47mA, V _{DS} =10V
Recommended driving voltage ¹	V _{DD}		15		V	Refer to driver GND
Drain Source leakage current	I _{DSS}	-	30	60	μA	V _{DS} = 650V
		-	75	200		V _{DS} = 650V T _J =150°C
Gate resistance	R _G	-	0.5	-	Ω	f=1Mhz
Drain-Source on state resistance	R _{DS(ON)}	-	8	10	mΩ	V _{GS} =0V I _D =100A
		15	17.5	20		V _{GS} =0V I _D =100A T _J =150°C
Reverse voltage drop- GaN non conductive	V _R	-	-	7.5	V	I _D =10A
		-	-	9.5		I _D =10A T _J =150°C
Reverse voltage drop- GaN conductive	V _R	-	-	0.08	V	I _D =10A, V _{GS} =0V
		-	-	0.175		I _D =10A, T _J =150°C V _{GS} =0V
Reverse recovery time	t _{rr}	-	-	0	ns	
Reverse recovery charge	Q _{rr}	-	-	0	nC	
Output Charge	Q _{oss}	-	-	420	nC	V _{DS} =400V
Dynamic						
Input capacitance	C _{iss}	-	1900	-	pF	f=1MHz V _{DS} =400V
Output capacitance	C _{oss}	-	500	-		
Reverse transfer capacitance	C _{rss}	-	70	-		
Effective Output Capacitance, Energy Related	C _{O(ER)}	-	1100	-	pF	V _{DS} = 0-400V
Turn-on delay time	t _{d(on)}	-	8	-	ns	V _{DS} =400V, V _{DD} =15V ¹ I _D =150A, BJT Gate Buffer R _{base} = 20Ω for ON & 2Ω for OFF
Fall time	t _f	-	6.5	-		
Turn-off delay time	t _{d(off)}	-	15	-		
Rise time	t _r	-	16	-		

1) In operation V_{gs} swings from -V_{DD} (OFF state) to 0V (ON state).

Electrical characteristics (T _J =25°C unless otherwise specified)						
Parameter	Symbol	Min	Typical	Max	Unit	Conditions
Gate Charge characteristics						
Gate to Source charge	Q _{GS}	-	8	-	nC	V _{GS} =0V to -14V V _{DS} =400V I _D =32A
Gate to Drain charge	Q _{GD}	-	130	-		
Total Gate charge	Q _G	-	200	-		



Typical Characteristics at 25C° (unless noted otherwise)

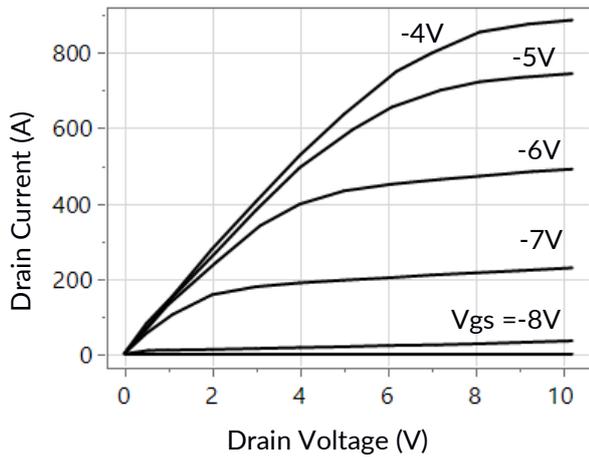


Figure 1 Output (Forward) Characteristics

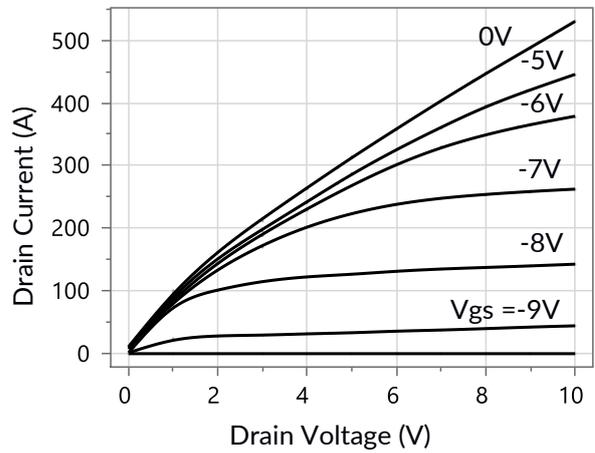


Figure 2 Output (Forward) Characteristics
 T_j=150C

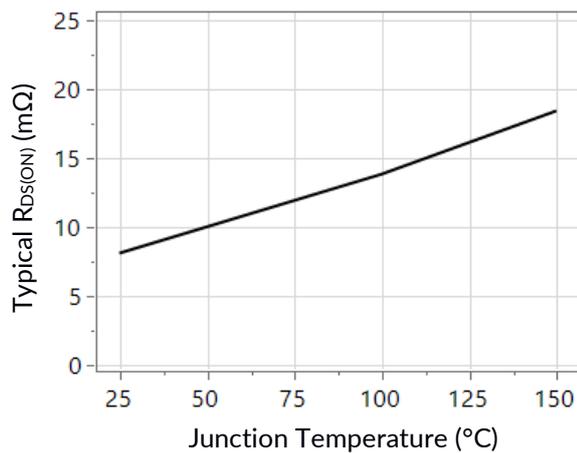


Figure 3 ON-State Resistance vs. Temperature

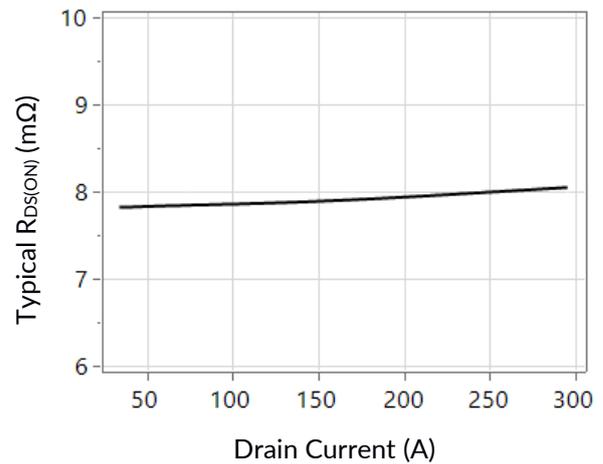
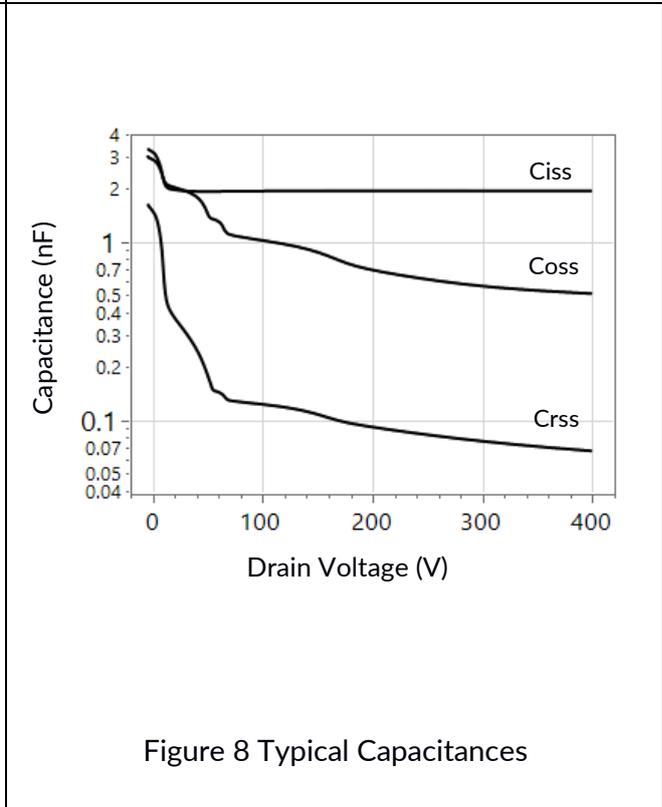
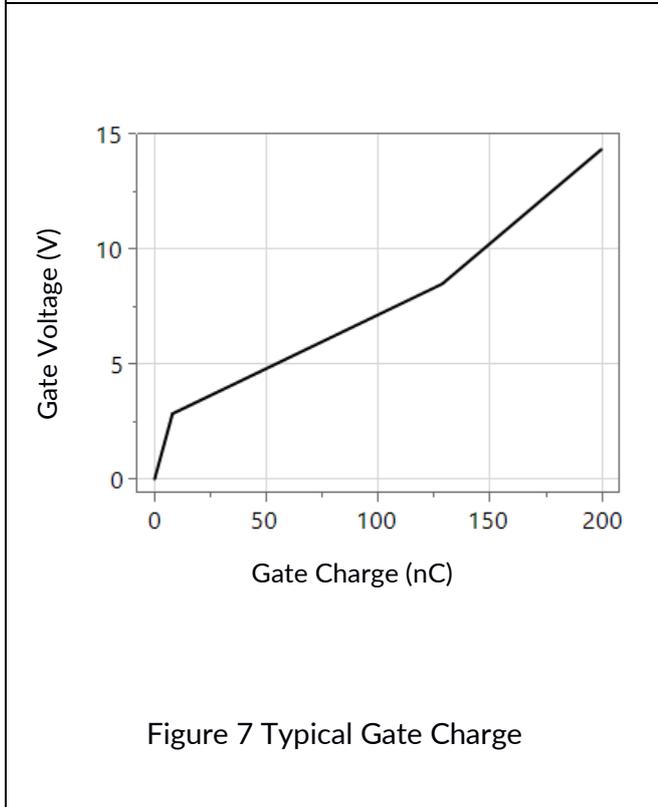
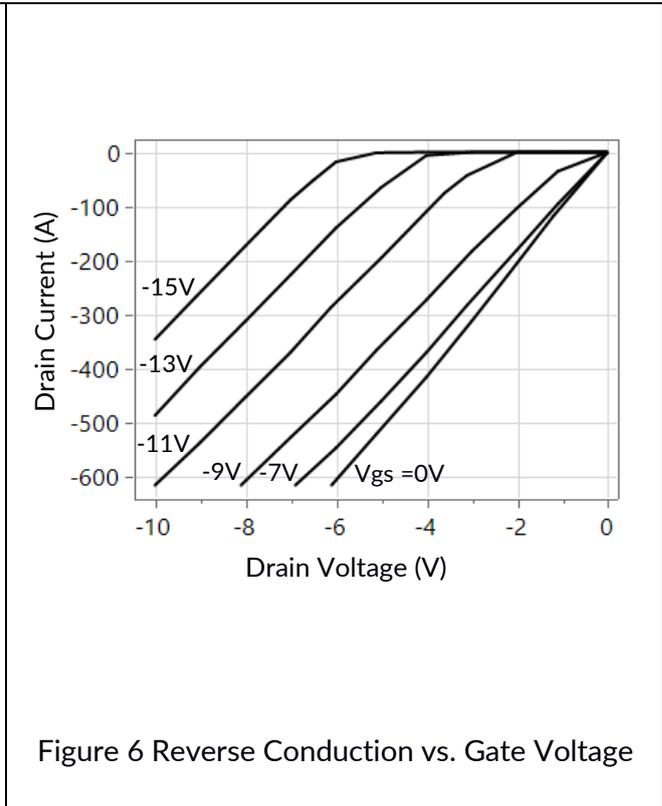
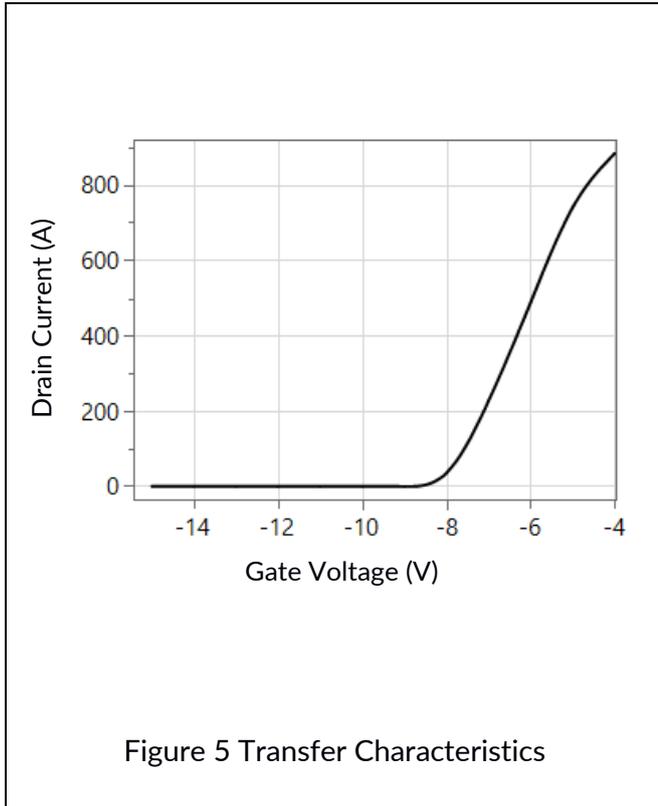


Figure 4 ON-State Resistance vs. Current at 25C



Typical Characteristics cont.



Typical Characteristics cont.

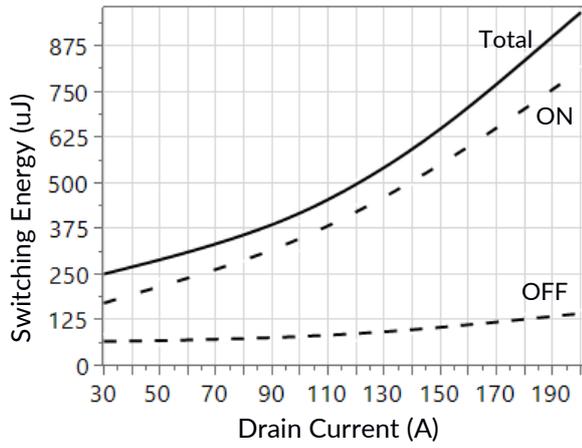


Figure 9 Typical Switching Energy vs Drain Current at 400V



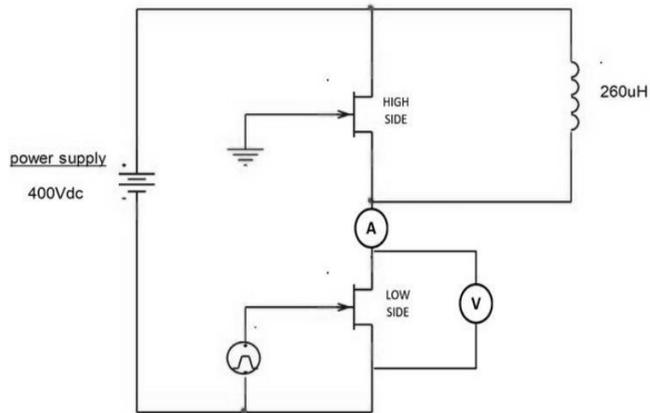


Fig.16: Switching parameters test circuit

Switching Time Waveforms

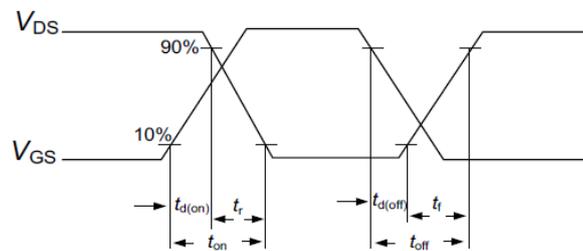
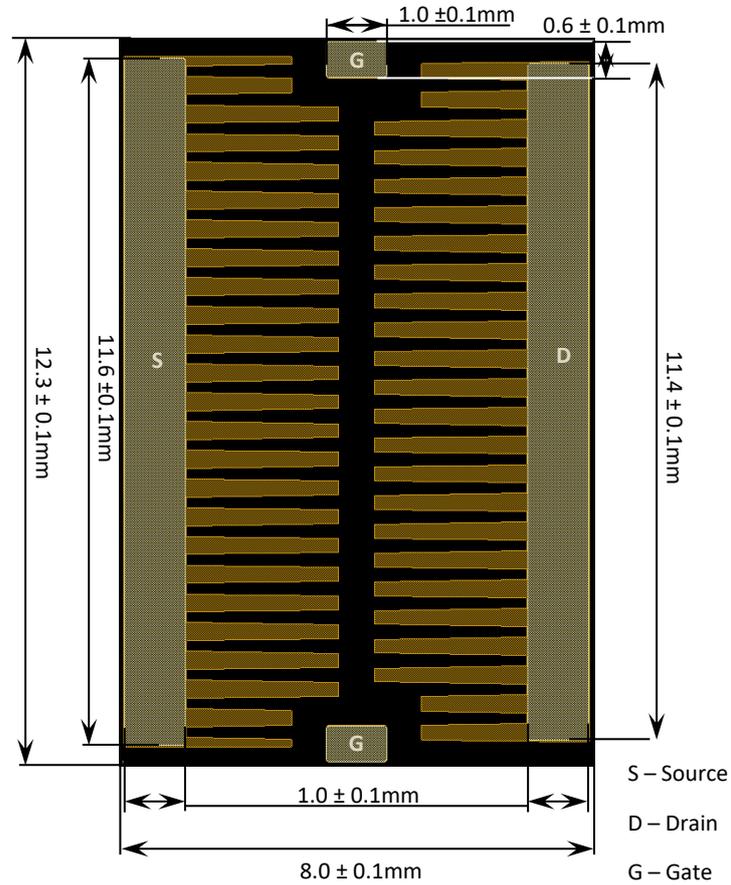


Fig.17: Switching time waveforms



Die Outlines:



Mechanical Characteristics						
Parameter		Min	Typical	Max	Unit	Material
Die thickness		260	270	280	μm	
Backside metal		0.1/0.3/0.01/1			μm	Ti/Ni/Ti/Ag
Topside pads metal		-	9	-	μm	Cu



Rev.	Date	Content of Change	Owner
1.0	15/06/2023	New datasheet and template under new part number	I.B
1.1	26/10/2023	Updated key performance parameters table	I.B

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